

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TSM104WAID"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TSM104WAID	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	D 16	9x3.9x1.75	218.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.086355	99.998842	999988	0.039474	395
Precious Metals	Silver	7440-22-4	0.000001	0.001158	12	0	0
Sub-Total			0.086356	100	1000000	0.039475	395
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.604068	80	800000	0.276129	2761
Thermoplastics	Epoxy	85954-11-6	0.151017	20	200000	0.069032	690
Sub-Total			0.755085	100	1000000	0.345162	3452
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	102.024208	97.24	972400	46.636925	466369
Copper and Its Alloys	Iron	7439-89-6	2.72792	2.6	26000	1.246977	12470
Copper and Its Alloys	Phosphorus	7723-14-0	0.15738	0.15	1500	0.071941	719
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.010492	0.01	100	0.004796	48
Sub-Total			104.92	100	1000000	47.960638	479606
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.827544	95.12	951200	0.378284	3783
Precious Metals	Gold	7440-57-5	0.006786	0.78	7800	0.003102	31
Precious Metals	Palladium	7440-05-3	0.03567	4.1	41000	0.016305	163
Sub-Total			0.87	100	1000000	0.397691	3977
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	96.5008	88	880000	44.112085	441121
Other Plastics and Rubber	Carbon Black	1333-86-4	0.32898	0.3	3000	0.150382	1504
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.60313	0.55	5500	0.275701	2757
Thermoplastics	Epoxy	85954-11-6	12.22709	11.15	111500	5.589202	55892
Sub-Total			109.66	100	1000000	50.127369	501274
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.471286	100	1000000	1.129665	11297
Sub-Total			2.471286	100	1000000	1.129665	11297
Total			218.762727			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meets J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.